ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: i nanufacture	f the item is an as r has engineering	sembly with low responsibility.	
2 21 1 IPC Web Site for Information on IPC-1752 Standard For				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg In					fg Informat	ion			
upplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2025-06	2025-06-04			
Contact Name Title - Contact			ct	1			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			wiro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represent			entative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version Manufacturing Site			Weight*	UOM	Unit Type		
	MURS3	URS360T3G REC SMC 3A 600		0V ULTFST TI	R	2025-06-04		V	VN5		250.86	mg	Each	
Ianufacturing Proccess Informa	tion		·										-	
Terminal Plating / Grid Array M	aterial Terminal Base Alloy		Alloy	J-STD-020 MSI	TD-020 MSL Rating		Peak Process Body Temperature Max Time at		e Max Time at Peak	ak Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU A		CU Alloy	1			260 C		30 seco		seconds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material Weight Unit of Me		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	39.16	mg	Supplier	Iron (Fe)	7439-89-6		0.0392	mg
			Supplier	Copper (Cu)	7440-50-8		39.1091	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0117	mg
Die	1.34	mg	Supplier	Silicon (Si)	7440-21-3		1.3266	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0134	mg
Die Attach Solder	2.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			А	Lead (Pb)	7439-92-1	7a	2.6085	mg
			Supplier	Tin (Sn)	7440-31-5		0.141	mg
Lead Frame	74.95	mg	Supplier	Iron (Fe)	7439-89-6		0.075	mg
			Supplier	Copper (Cu)	7440-50-8		74.8526	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0225	mg
Mold Compound-Black	131.93	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		13.193	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6596	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		19.1298	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		85.7545	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.193	mg
Plating	0.66	mg	Supplier	Tin (Sn)	7440-31-5		0.66	mg